Kemet Double Sided Lapping Polishing Machines

Kemet Dual Face Machines are advanced solutions designed for grinding, lapping, and polishing both flat surfaces of components simultaneously. These machines are capable of handling a wide variety of materials, ensuring high precision and consistency in processing. With the ability to achieve extremely tight tolerances, they are especially effective for working with delicate or fragile parts. The smooth operation of the grinding or lapping process is ensured by driving five carriers, which maintain stable action throughout.

The machines are equipped with variable plate and carrier speeds, controlled through an AC frequency drive, allowing for optimal adjustment based on specific needs. Additionally, Kemet provides custom plates tailored for fine grinding, standard grinding, or lapping, ensuring peak performance for each application.

Several optional features enhance the functionality of Kemet Dual Face Machines, including Automatic Thickness Control, Load Cell Pressure Control for precise force management, and an intuitive HMI Touch Panel for easy operation and monitoring.

These machines are ideal for a range of high-precision applications, such as processing sapphire and silicon wafers, precision optics, filter glass, sapphire watch glass, quartz crystals, and components for disk drives. Kemet also offers a comprehensive range of lapping and polishing systems to meet various industrial needs. For specialised requirements, Kemet can develop custom machines tailored to specific applications, providing versatile and reliable solutions for precise material finishing.

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Products of interest *

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Kemet DS 6, 9, 12 Series With Analogue Control

Specification	DS 6	DS 9	DS 12
Diameter of Lapping Plate (mm)	Dia. 374 x Dia. 150mm	Dia. 645 x Dia. 235mm	Dia. 753 x Dia. 260mm
Maximum Diameter of Products (mm)	Dia. 110mm	Dia. 180mm	Dia. 220mm
Diameter of Carrier (PCD)(mm)	Dia. 139.3 (PCD)	Dia. 228.5 (PCD)	Dia. 283.6 (PCD)
Number of Carrier	5 Pcs	5 Pcs	5 Pcs
Minimum Thickness of Products (mm)	0.08mm	0.3mm	0.3mm
Rotating Speed of Lower Lapping Plate (RPM)	0 - 60 RPM	0 - 60 RPM	0 - 60 RPM
Reversal mechanism of Carrier	CW & CCW	CW & CCW	CW & CCW
Size (mm)	930 (W) X 700 (L) X 1930 (H)	1740 (W) X 1070 (L) X 2090 (H)	1610 (W) X 1200 (L) X 2400 (H)
Estimated Weight	800 KGS	1800 KGS	2300 KGS
Electric Supply	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz



Kemet DS 6, 9, 12 Series With HMI Control

Specification	DS 6	DS 9	DS 12
Diameter of Lapping Plate	Dia. 374 x Dia. 150 mm	Dia. 630 x Dia. 240 mm	Dia. 753 x 260 mm
Maximum Diameter of Products	Dia. 110 mm	Dia. 180 mm	Dia. 220 mm
Diameter of Carrier (PCD)	Dia. 139.3 (PCD)	Dia. 228.5 (PCD)	Dia. 283.6 (PCD)
Number of Carrier	5 Pcs	5 Pcs	5 Pcs
Minimum Thickness of Products	0.08mm	0.3mm	0.3mm
Rotating Lapping Speed of Lower Plate (RPM)	0 - 60 RPM	0 - 60 RPM	0 - 60 RPM
Reversal Mechanism of Carrier	CW & CCW	CW & CCW	CW & CCW
Machine Dimension [mm]	930 (W) X 700 (L) X 1930 (H)	1480 (W) X 880 (L) X 2400 (H)	1610 (W)X 1200 (L)X 2400 (H)
Estimated Weight	800 kgs	1800 kgs	2300 kgs
Electric Supply	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz



Kemet DS 16, 18 Series with HMI Control

Specification	DS 16	DS 18
Diameter of Lapping Plate	Dia. 1155 x ID 360 mm	Dia. 1262 x ID 535 mm
Maximum Diameter of Products	Dia. 390 mm	Dia. 390 mm
Diameter of Carrier (PCD)	Dia. 423.33 (PCD) mm	Dia. 423.33 (PCD) mm
Number of Carrier	5 Pcs	6 Pcs
Minimum Thickness of Products	0.3 mm	0.3 mm
Rotating Speed of Lower Lapping Plate (RPM)	0 - 60 RPM	0 - 60 RPM
Reversal Mechanism of Carrier	CW & CCW	CW & CCW
Machine Dimension [mm]	2020 (W) x 1500 (L) x 2260 (H)	2530 (W) x 1900 (L) x 2260 (H)
Estimated Weight	6500 kgs	7000 kgs
Electric Supply	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz

